

N-Channel 45-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^{a, c}	Q_g (Typ.)
45	0.0057 at $V_{GS} = 10$ V	75	240 nC
	0.0060 at $V_{GS} = 4.5$ V	70	

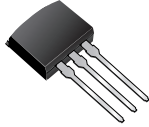
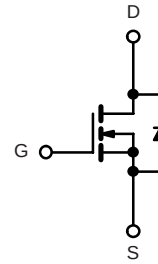
FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

- Synchronous Rectification
- Power Supplies


RoHS
 COMPLIANT

I²PAK
 (TO-262)

D²PAK
 (TO-263)


N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	45	V
Gate-Source Voltage		V_{GS}	± 25	
Continuous Drain Current ($T_J = 175^\circ\text{C}$)	$T_C = 25^\circ\text{C}$	I_D	75 ^{a, c}	A
	$T_C = 70^\circ\text{C}$		70 ^c	
	$T_A = 25^\circ\text{C}$		29 ^b	
	$T_A = 70^\circ\text{C}$		23 ^b	
Pulsed Drain Current		I_{DM}	250	
Avalanche Current Pulse	$L = 0.1$ mH	I_{AS}	80	
Single Pulse Avalanche Energy		E_{AS}	320	V
Continuous Source-Drain Diode Current	$T_C = 25^\circ\text{C}$	I_S	110 ^{a, c}	A
	$T_A = 25^\circ\text{C}$		2.6 ^b	
Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	312 ^a	W
	$T_C = 70^\circ\text{C}$		200	
	$T_A = 25^\circ\text{C}$		3.13 ^b	
	$T_A = 70^\circ\text{C}$		2.0 ^b	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	Steady State	R_{thJA}	32	40	$^\circ\text{C/W}$
Maximum Junction-to-Case	Steady State	R_{thJC}	0.33	0.4	

Notes:

 a. Based on $T_C = 25^\circ\text{C}$.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 110 A.

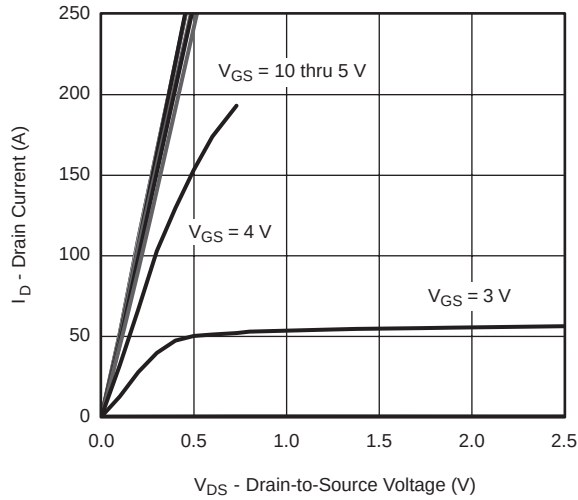
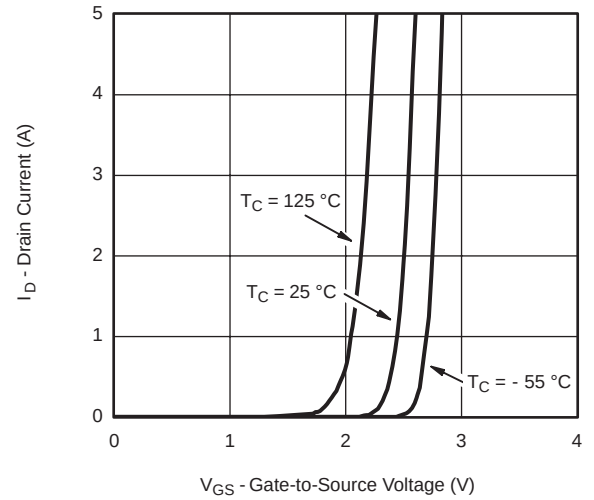
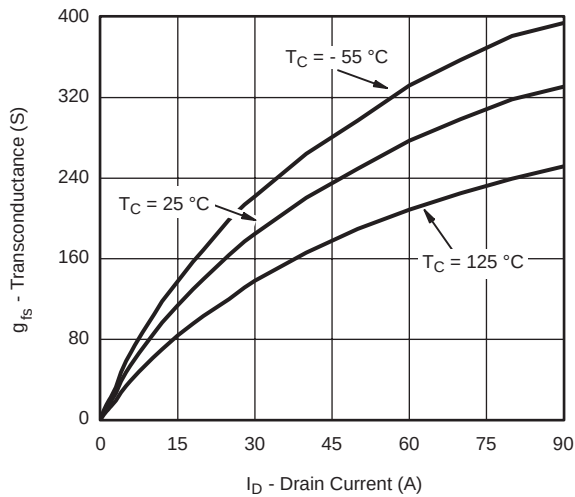
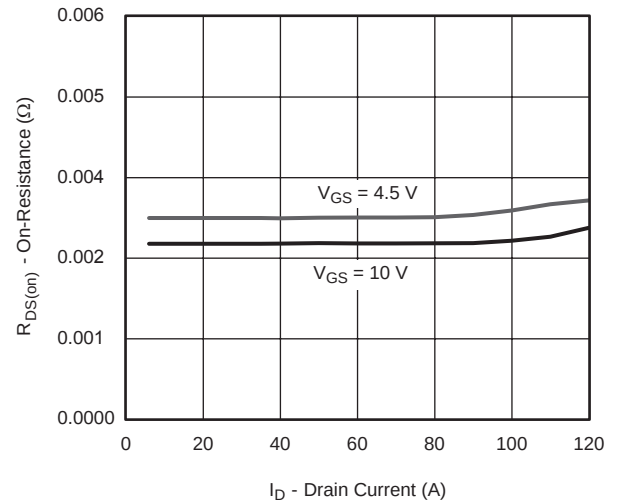
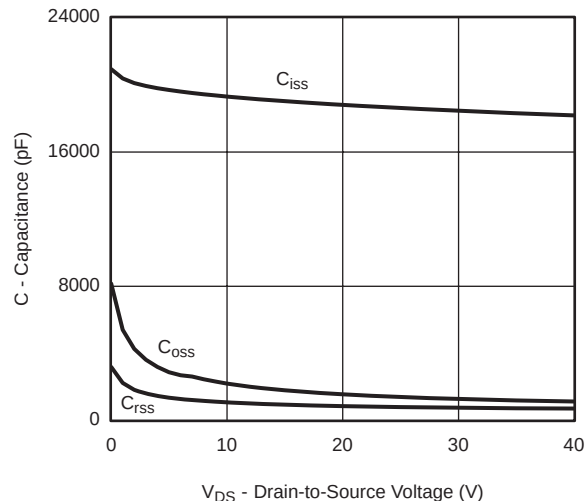
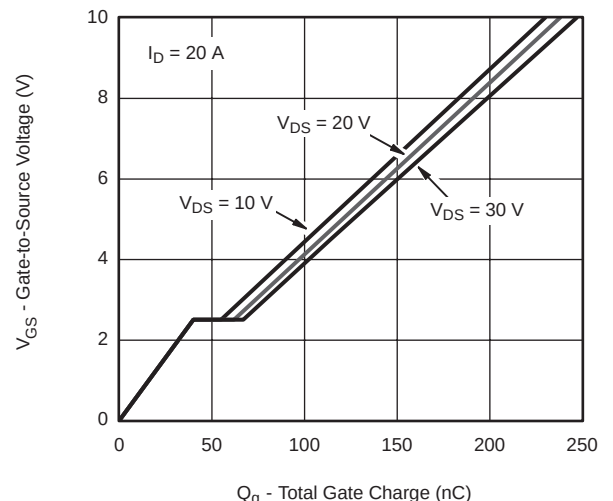
SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	40			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		41		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 8		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.2		2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	μA
		V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C			10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	120			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A		0.0057		Ω
		V _{GS} = 4.5 V, I _D = 20 A		0.0060		
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 30 A		180		S
Dynamic ^b						
Input Capacitance	C _{iSS}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz		18800		pF
Output Capacitance	C _{oSS}			1550		
Reverse Transfer Capacitance	C _{rSS}			850		
Total Gate Charge	Q _g	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 20 A		240	360	nC
Gate-Source Charge	Q _{gs}			40		
Gate-Drain Charge	Q _{gd}			22		
Gate Resistance	R _g	f = 1 MHz		0.85	1.3	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = 20 V, R _L = 1.0 Ω I _D ≅ 20 A, V _{GEN} = 10 V, R _g = 1 Ω		20	30	ns
Rise Time	t _r			11	17	
Turn-Off Delay Time	t _{d(off)}			77	115	
Fall Time	t _f			10	15	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 20 V, R _L = 1.0 Ω I _D ≅ 20 A, V _{GEN} = 4.5 V, R _g = 1 Ω		102	155	
Rise Time	t _r			62	95	
Turn-Off Delay Time	t _{d(off)}			180	270	
Fall Time	t _f			60	90	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			110	A
Pulse Diode Forward Current ^a	I _{SM}				200	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		50	75	ns
Body Diode Reverse Recovery Charge	Q _{rr}			70	105	nC
Reverse Recovery Fall Time	t _a			30		ns
Reverse Recovery Rise Time	t _b			20		

Notes:

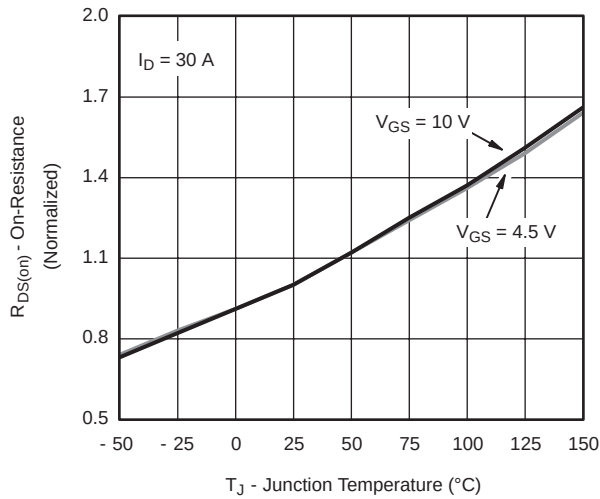
a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

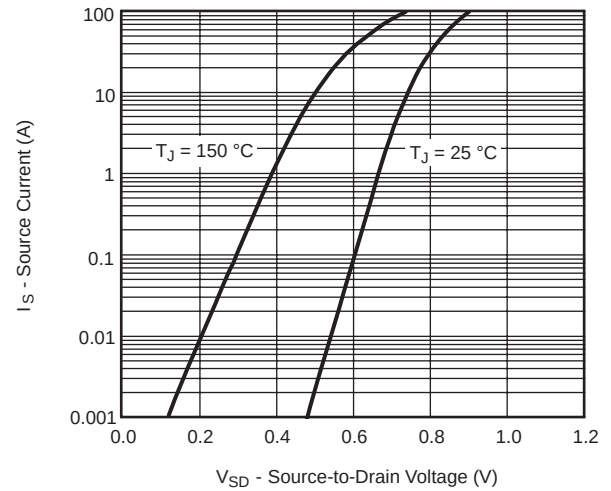
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Output Characteristics

Transfer Characteristics

Transconductance

On-Resistance vs. Drain Current

Capacitance

Gate Charge

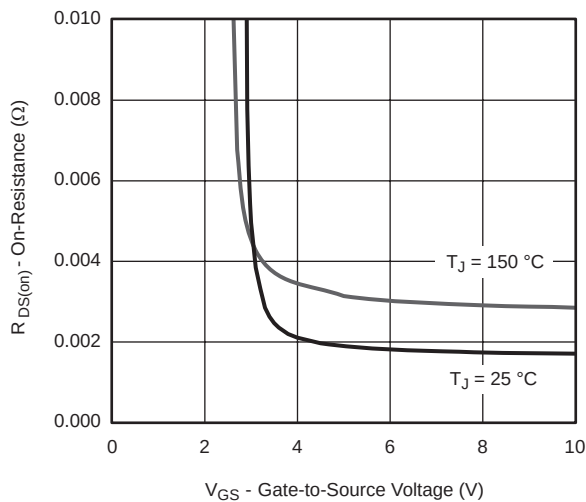
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



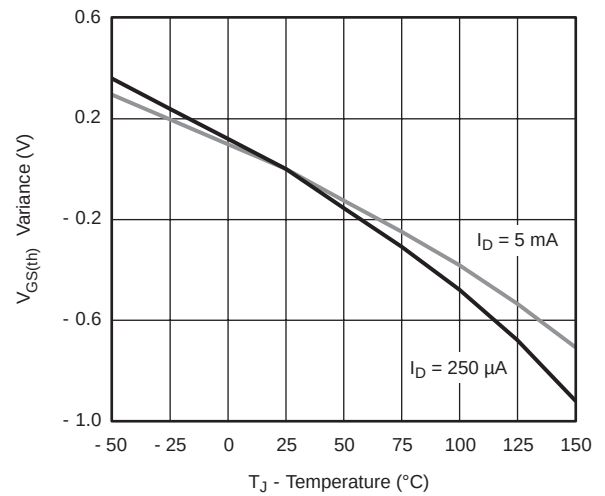
On-Resistance vs. Junction Temperature



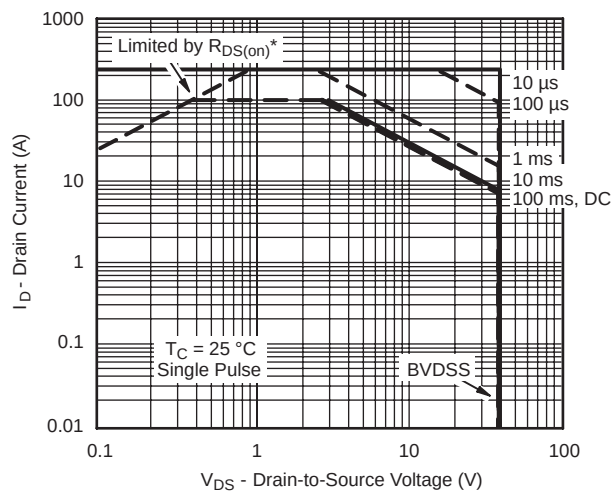
Forward Diode Voltage vs. Temperature



On-Resistance vs. Gate-to-Source Voltage



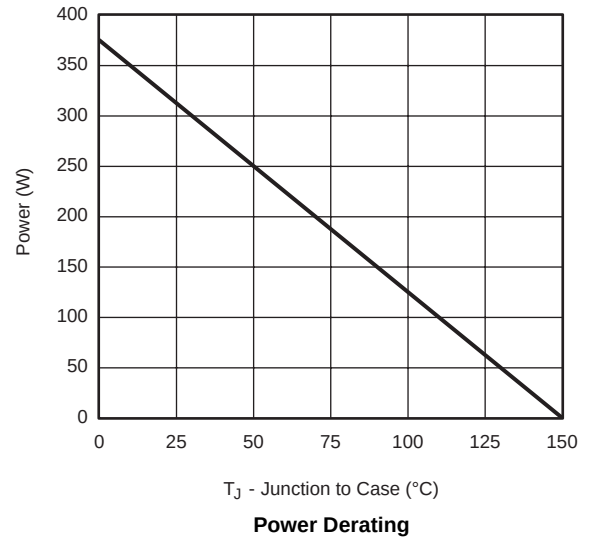
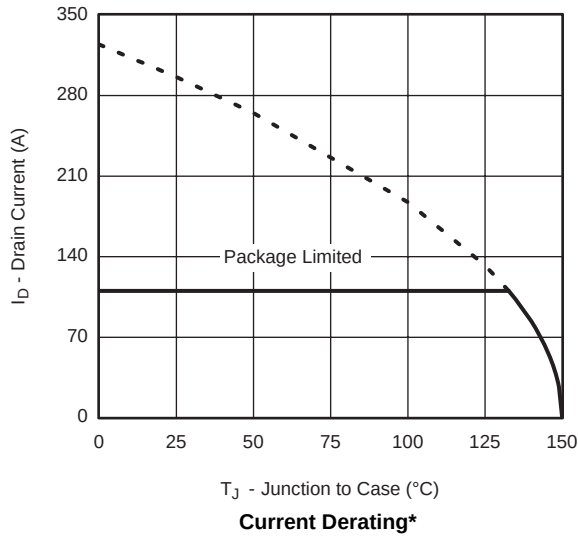
Threshold Voltage



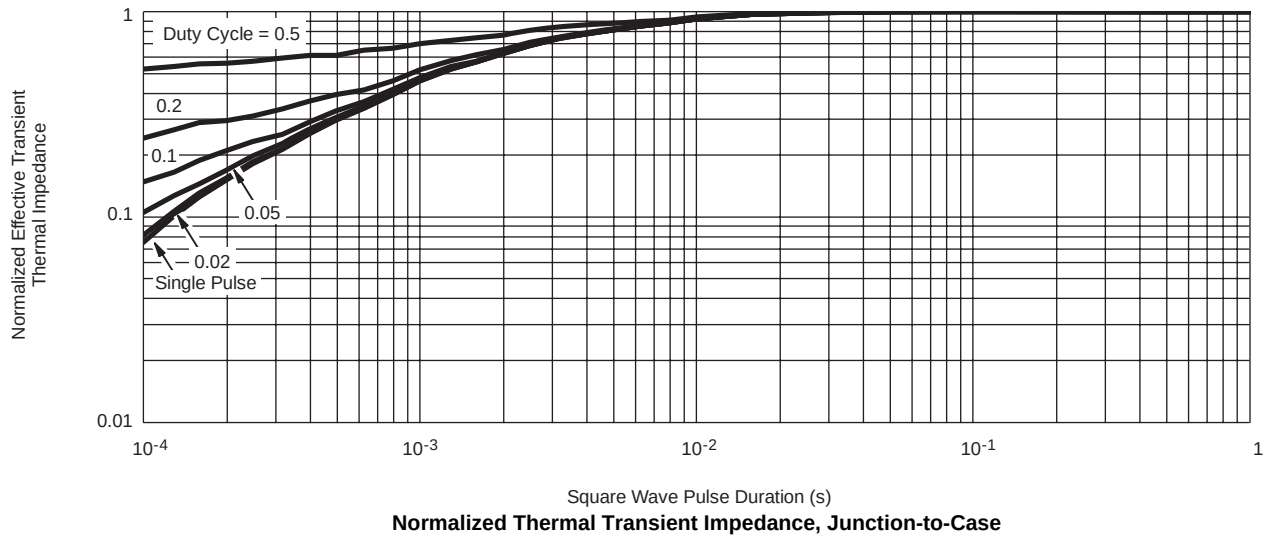
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Technical drawing of a mechanical part, showing multiple views and annotations:

- Main View (Top Left):** Shows the front view of the part. Dimensions include E (width), $L1$ (height from datum A), D (total height), H (height from base), $L2$ (height from base), $2 \times b2$ (width of the base), $2 \times b$ (width of the base), and $2 \times e$ (width of the base). Datum A is indicated by a triangle with the letter A. Section lines 1, 2, 3, and 4 are shown. A detail callout "Detail A" is present.
- Detail A (Top Right):** A circular detail view of the part, showing a curved surface. Dimensions include A (width), $c2$ (width), and c (width). A detail callout "Detail A" is present.
- Seating Plane (Middle Right):** A detail view of the seating plane, showing a gauge plane and a seating plane. Dimensions include 0° to 8° (angle), $L3$ (width), $L4$ (width), $A1$ (width), and B (width). A detail callout "Detail A" is present.
- Section B - B and C - C (Bottom Left):** A cross-sectional view of the part, showing the base metal and plating. Dimensions include $b1, b3$ (width), $c1$ (height), $(b, b2)$ (width), and (c) (height). A detail callout "Detail A" is present.
- View A - A (Bottom Right):** A cross-sectional view of the part, showing the base metal and plating. Dimensions include E (width), $D1$ (height), $E1$ (width), and 4 (width).
- Annotations:**
 - (Datum A):** Indicated by a triangle with the letter A.
 - Lead tip:** Indicated by an arrow pointing to the lead tip.
 - Base metal:** Indicated by a triangle with the letter A.
 - Plating:** Indicated by a triangle with the letter A.
 - Seating plane:** Indicated by a triangle with the letter A.
 - Gauge plane:** Indicated by a triangle with the letter A.
 - Detail "A":** Indicated by a triangle with the letter A.
 - Rotated 90° CW scale 8:1:** Indicated by a triangle with the letter A.
 - Scale: none:** Indicated by a triangle with the letter A.

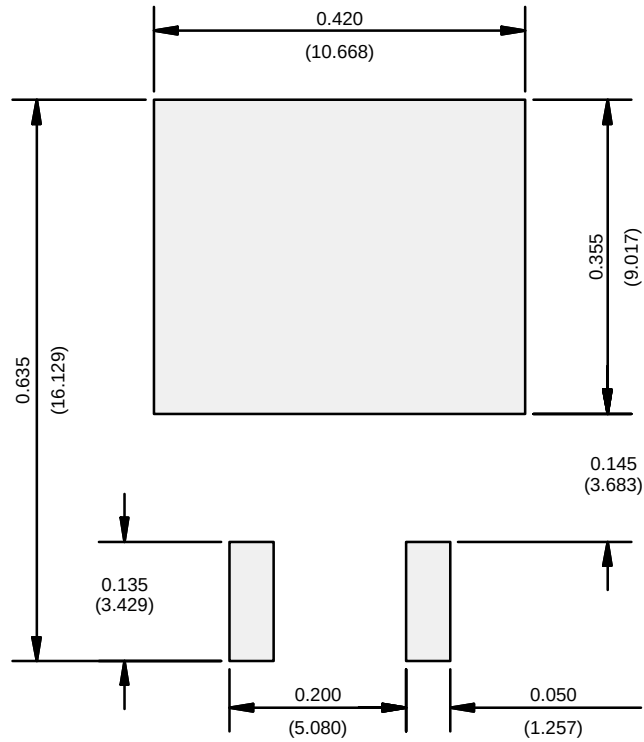
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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